

TG Series LED

TGB-2823D-1820BB



特性 Features

- 提供3step, 2step, 1.5step分bin出货方案 Available in 3-step, 2-step and 1.5-step EasyWhite® bins
- 可提供70, 80, 90, 95, 97显色方案 Available in 70, 80, 90, 95 and 97 minimum Ra options
- 低热阻 Low thermal resistance
- 符合 ROHS、REACH 标准 RoHS and REACH compliant

描述 Description

同一方COB产品具有高光效，高显指，低功耗，发光角度广等一系列特性，这些特性使其成为照明应用的首选。

The TYF COB package has high efficacy, high Ra, low power consumption, wide viewing angle and a compact form factor. These features make the package an ideal LED for lighting applications.

应用 Applications

- 舞台成像灯、舞台聚光灯
Stage image lamp, Stage spotlight
- 摄影灯、摄影补光灯
photographic lamp, Photographic fill light

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1	2	3	–	4	5	6	7	8	–	9	10	11	12	13	14	–	15	16	17	18	19
T	G	B	–	2	8	2	3	D	–	1	8	2	0	B	B	–	K	4	0	B	0

2、外形尺寸 Dimensions

Technical drawing of a circular part with the following dimensions and tolerances:

- Overall width: 28,00
- Overall height: 28,00
- Inner diameter: $\varnothing 23,00$
- Outer diameter: $\varnothing 3,20$
- Top-left corner radius: 2,00
- Bottom-right corner radius: 3,00
- Top-left feature: Orange oval with a plus sign (+)
- Bottom-right feature: Orange square with a minus sign (-)

All dimensions area in mm tolerance is $\pm 0.2\text{mm}$ unless otherwise noted.

3、极限参数 Absolute Maximum Ratings

项目 Item	符号 Symbol	Min	Typ	Max	单位 Unit
极限功率 Limiting power	P	—	300.0	390.0	W
正向电压 Forward Voltage	VF	54	56	58	V
正向电流 Forward Current	IF	—	5200	—	mA
工作焊点温度 Operating Temperature	TC	-40	—	85	° C
结点温度 Junction Temperature	Tj	—	—	125	° C
储存温度 Storage Temperature	Tstg	-40	—	105	° C
静电击穿电压 ESD Sensitivity	ESD	—	—	2000	V
反向电压 Reverse Voltage	VR	Reverse testing is not allowed			/
反向电流 Reverse Current	IR			5	uA
焊接温度 Soldering Temperature	Tsld	350° C/3-5sec.			°C/S

补充说明 Additional Remarks

- 极限功率和正向电流 是指模块温度通过使用合适的散热体下的最大设置数值；

Max power and positive current mean the maximum setting value of the bottom temperature of led light source by using the appropriate heat sink.

- 最初连接错误的反向电压，超出将可能损坏模组；

Connection error and off-limits voltage may damage LED chip.

4、光电特性 Electrical-Optical characteristics (T j = 25℃)

表 1: 在 Tj=25℃时测试的光电参数

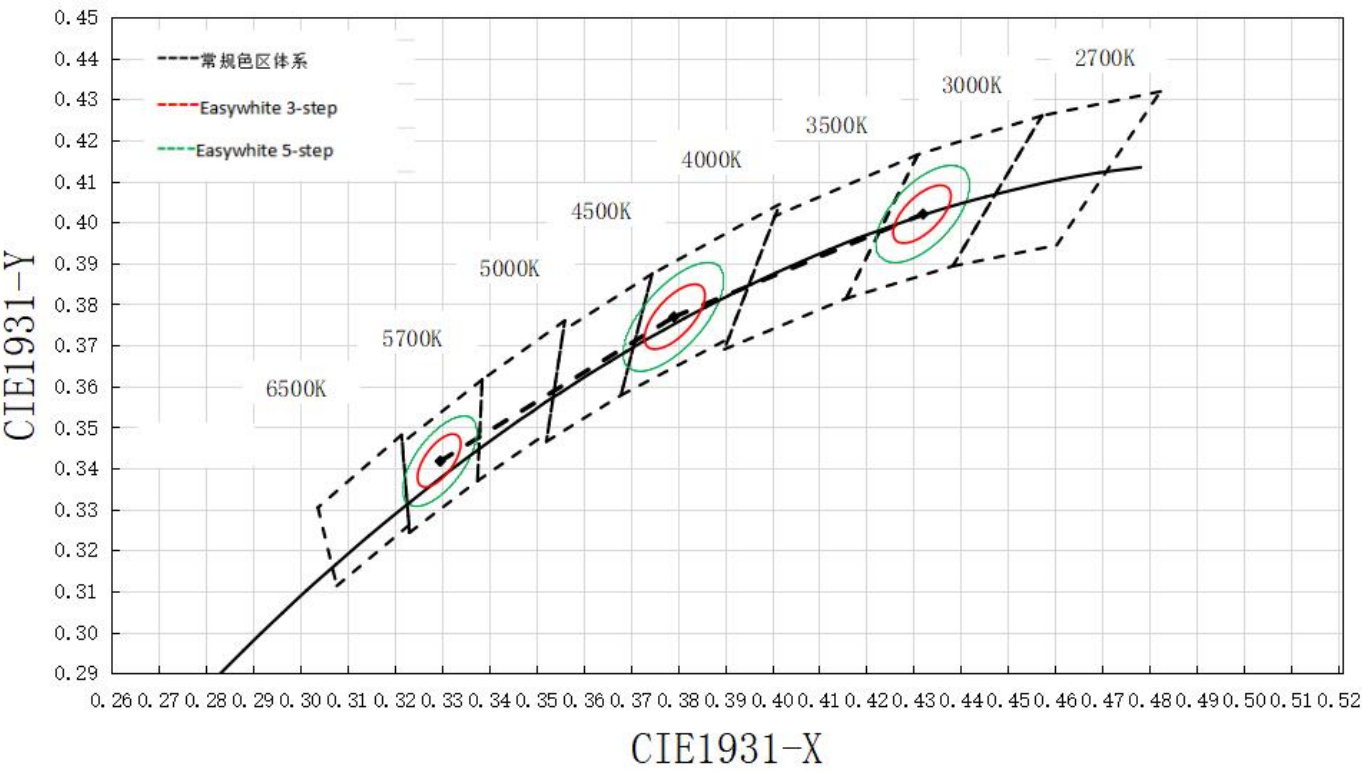
Product 产品系列	CRI 显色	CCT 色温 (K)	Luminous Flux 光通量 (lm) 5200MA	Efficacy 光效 (lm/W) 5200MA	Voltage 电压 (V) VF5200MA	Part Number 产品编码
TGB-2823D-1820BB	95	3000	26208-29120	90-100	54-58	TGB-2823D-1820BB-K31A4
		4000	26208-29120	90-100		TGB-2823D-1820BB-K40B0
		5700	26208-29120	90-100		TGB-2823D-1820BB-K57B4

说明:

表1备注Table 1 note:

- 测试环境温度 25 ℃, 若使用不同电流或不同的环境温度测试, 会引起色温及电压的变化;
Testing environment temperature 25 ℃, and CCT and voltage will changed if tested in different current and environment temperature.
- 不同标准测试仪正常测试允许公差: 电压±0.1V , 流明±5% , 显指±2, 色坐标±0.005;
Tolerance among different testing machine: Voltage:±0.1V, Lumen±5%, CRI±2, Color coordinate ±0.005.

5、色区参考图 The reference map color area



CIE(X, Y)坐标 CIE coordinates (X, Y)

Nominal CCT	Center Point		MAJOR AXIS (a , b)			Ellipse
	X	Y	2-Step	3-Step	5-Step	Rotation
3000K	0.431	0.402	(0.00556, 0.00272)	(0.00834, 0.00408)	(0.0139, 0.0068)	53.22
4000K	0.3782	0.3769	(0.00556, 0.00272)	(0.00834, 0.00408)	(0.0139, 0.0068)	53.72
5700K	0.3287	0.3417	(0.00548, 0.00236)	(0.00822, 0.00354)	(0.0137, 0.0059)	59.09

备注/Postscript:
色域范围为同一方自定义色区，色域范围可控制在自定义色区所规范的SDCM≤2。The color gamut range is the TYF custom color zone, which can be controlled in the SDCM 2 specified by the custom color area.

6、典型特性曲线/Typical Characteristic Curves

(1) 典型光谱分布

Typical spectral distribution

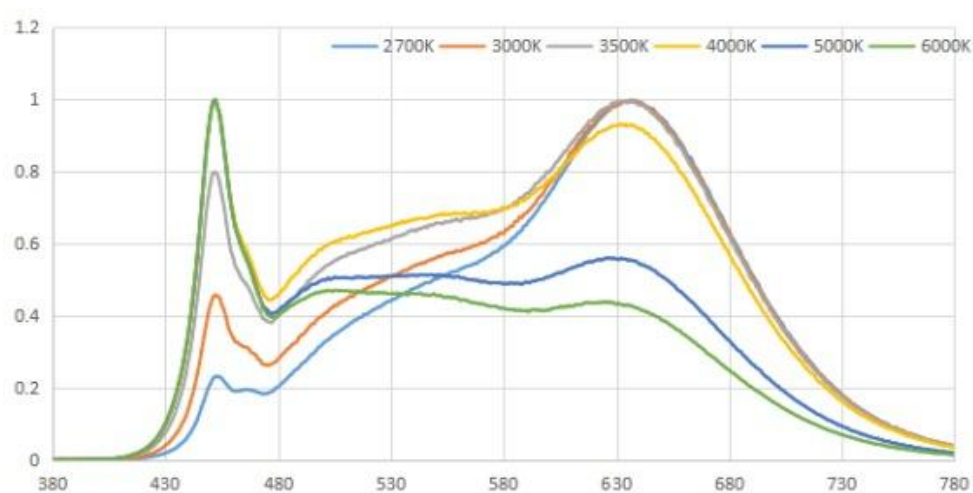
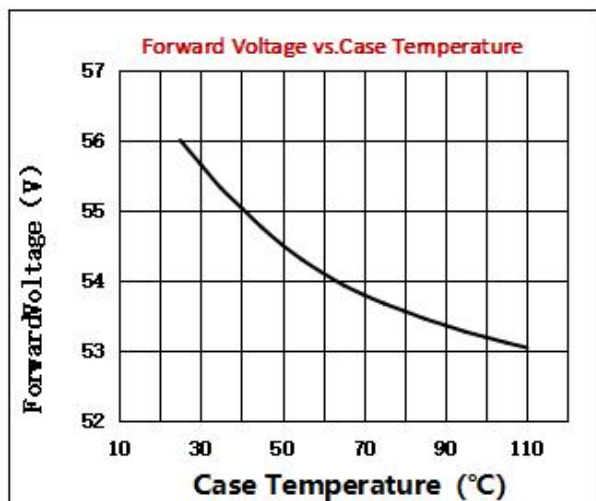
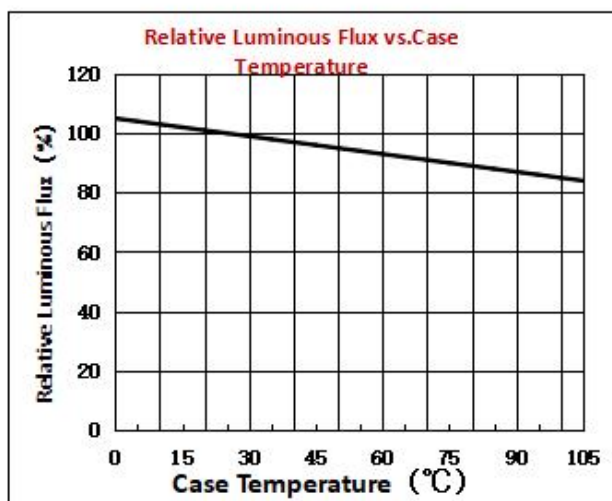
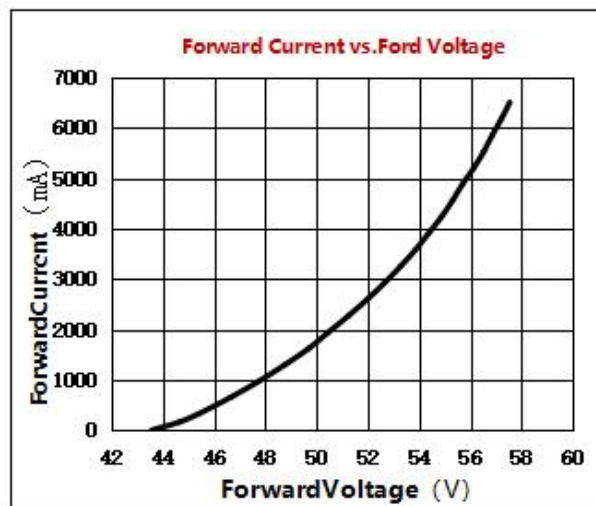
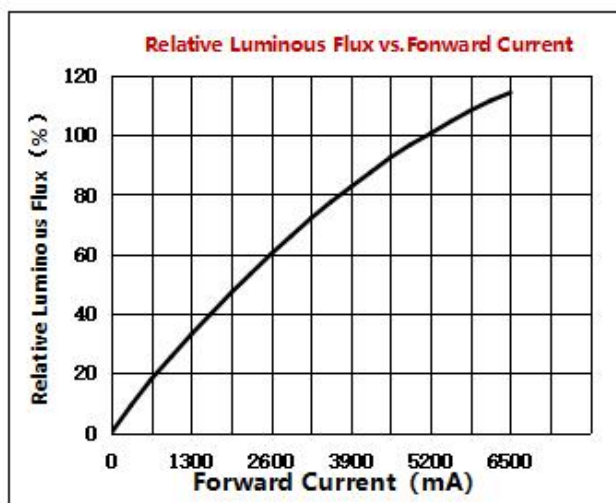
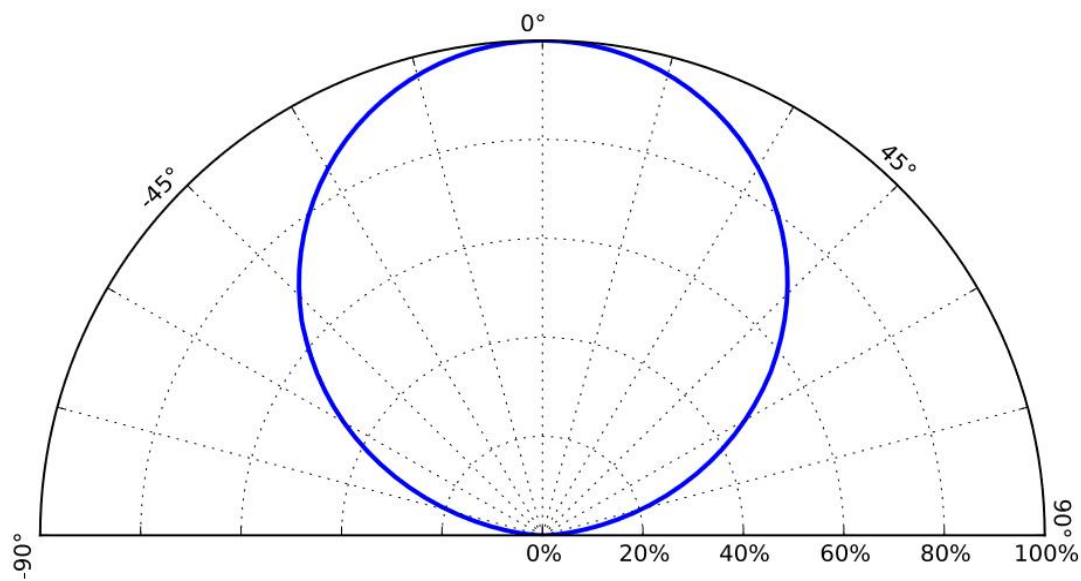


Figure 1a. Typical normalized power vs. wavelength for at test current, RA95 $T_j = 25^\circ \text{C}$.

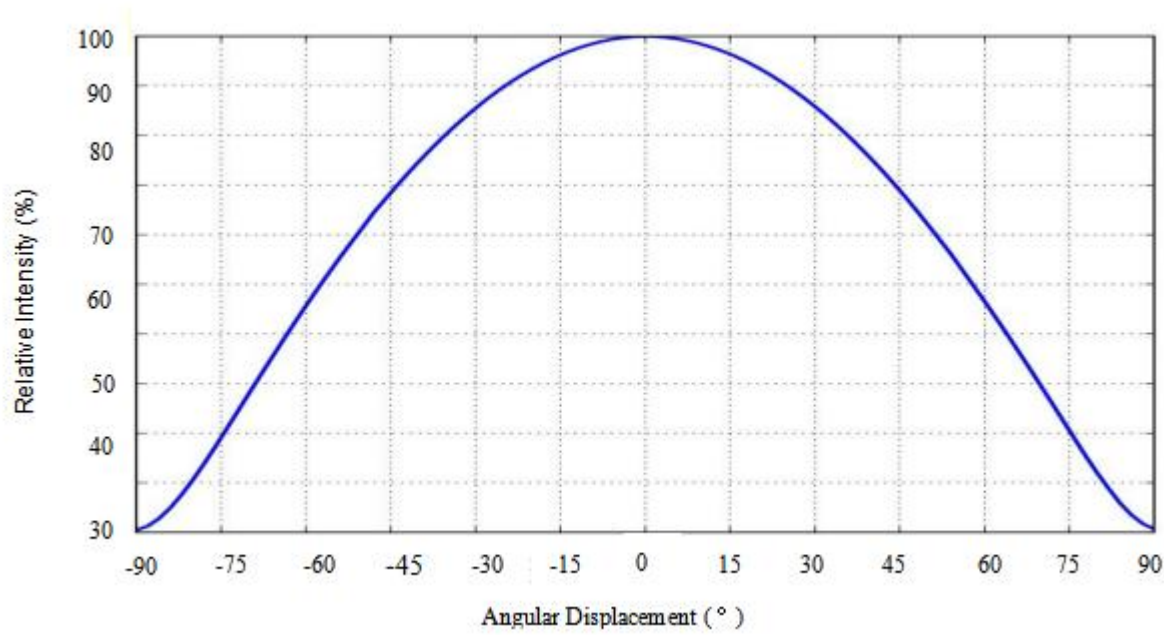
Light Output Characteristics



Radiation Pattern Characteristics



Typical radiation pattern for T at test current, $T_j = 25^{\circ}\text{C}$.



7、可靠性试验/Reliability Test Items And Conditions

测试项目和测试条件 Testing items and testing conditions

序号 No.	试验项目 Test Item	参考标准 reference standard	试验条件 Test condition		样品数量 Sample Quantity	失效数量 Failure Quantity
1	高低温冲击 Thermal shock	JESD22-A104E	(-40℃ 15min)-----+120℃ (15min), ↑ ↓ 10 mins, 200cycles		22pcs	0
2	高温存放 High Temperature Storage	JESD22-A103D	+100℃, 1000h		22pcs	0
3	低温存放 Low Temperature Storage	JESD22-A119	-40℃, 1000h		22pcs	0
4	高温高湿老化 High Temperature, High Humidity, Aging Test	JESD22-A101C	T=+85℃, R H=85%	IF=5200MA 1000h	22pcs	0
5	高温使用寿命 High-temperature operation	IES LM80-2015	T=+105℃,	IF=5200MA 1000h	22pcs	0
6	低温使用寿命 Low temperature operation	JESD22-A108D	T=-40℃,	IF=5200MA 1000h	22pcs	0
7	回流焊湿度敏感实验 Moisture/Reflow Sensitivity Test	J-STD-020E	Precondition: 60℃. 60%RH. 168H Tslid=260℃. 10sec. 3 Reflows		22pcs	0

失效判定标准 Criteria For Judging Damage

项目 Test Items	测试条件 Test Condition	判定标准 Criteria For Judgement	
		Min. 最小	Max. 最大
正向电压 Forward Voltage	IF=5200MA	/	U. S. L*1. 1
反向电流 Reverse Current	VR=5V	/	U. S. L*2. 0
光通量 Luminous Flux	IF=5200MA	L. S. L*0. 7	/

8、包装/Packaging

静电袋标签 Electrostatic bag label

TYF LED

Natural Light for Healthy Life

TYPE : TGB-2823D

P/N : TGB-2823D-1820BB-K40B0



L/N : D2212018 QTY : 50Pcs



XY : 40B0

Bin : 2SDCM

Code : 01

SPEC : 300W\54-58V\5200mA\RA95\4000K\90-100Lm/w

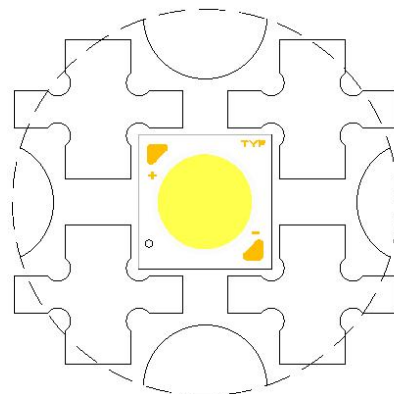
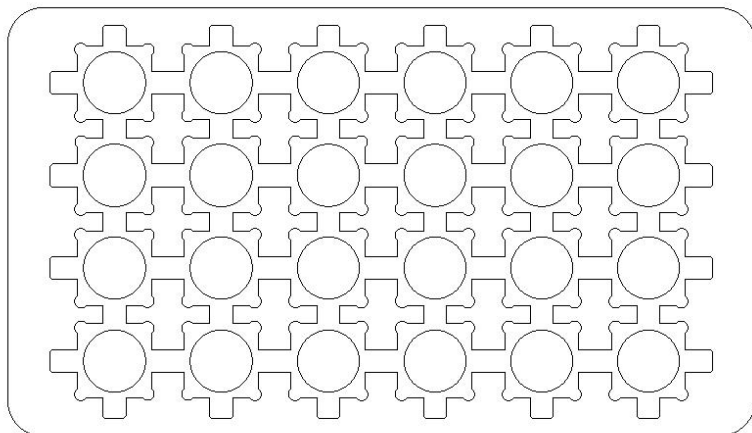
02



背面镭射图示/Laser image on the back

1204P7	Series parallel+Luminance level
30S0H	CCT+Ra
XXX..	Production NO
(工单号)	批次号

托盘包装图/Tray packing drawing



备注 Postscript:

- 每个吸塑盘可以包装 1~18 pcs COB/Each blister disk can pack 1 to 18 pcs COB
- 每个吸塑盘上面会贴一张标签/A label will be attached to each blister disk
- 吸塑盘最终会静电袋真空包装/Blister disk will be vacuum packed with electrostatic bag finally

9、使用注意事项 Caution

1.推荐的焊接条件 Recommended welding conditions

对于手工焊接。请使用无铅焊接，焊接应该通过焊接钻头被植入且温度低于 350℃，并在 3.5s 之内被完成。在进行焊接时，不应对外树脂部件施加外力。下一次焊接工艺应在产品恢复到环境温度后进行。

For manual soldering. Please use lead-free soldering and the soldering shall be implemented using a soldering bit at a temperature lower than 350C, and shall be finished within 3.6 seconds for one land. No external force shall be applied to resin part while soldering is implemented. Next process of soldering should be carried out after the product has return to ambient temperature.

2.化学接触危害 Attention

接触一些常规使用到光源制造和集合装配上的化学物质能引起 LED 系列的损坏，请参阅同一方安装说明以获得更多信息。

Exposure to some chemicals commonly used in luminaire manufacturing and assembly can cause damage to the LED array. Please consult TYF Installation Instruction for additional information.

3.静电防护 Electrostatic protection

LED 属于 I 级静电敏感器件，接触、使用过程做好防静电保护；

LED belong to grade I electrostatic sensitive device, please do ESD protection when touch and use

4.接触发光面风险 Risk of contact with light-emitting surfaces

避免与 LES 接触。不要触摸 LED 系列的 LES 或在 LES 上(黄色荧光粉树脂区域)施加压力。接触可能对 LED 系列造成损坏。光学和反射器不得安装在与 LES(黄色荧光粉树脂区)接触的地方。光学器件可安装在 LED 系列的塑料外壳的上表面。使用 LED 系列外壳、边缘和/或安装孔的机械特性来根据需要进行定位和保护光学器件

Avoid any contact with the LES. Do not touch the LES of the LED array or apply stress to the LES (yellow phosphor resin area). Contact may cause damage to the LED array. Optics and reflectors must not be mounted in contact with the LES (yellow phosphor resin area). Optical devices may be mounted on the top surface of the plastic housing of the TYF LED array. Use the mechanical features of the LED array housing, edges and/or mounting holes to locate and secure optical devices as needed

5.储存条件 Risk of contact with light-emitting surfaces

LED 必须存放在清洁的环境中。密封袋的保质期为 12 个月, 温度为 0~40℃, 相对湿度为 0~90%
撕开包装剩余的 LED 需重新密封包装, 放置在干燥的环境

LEDs must be stored in a clean environment. Shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH.

Repack unused products with anti-moisture packing, fold to close any opening and then store in a dry place